

### General Description

The WST6008 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST6008 meet the RoHS and Green Product requirement with full function reliability approved.

### Features

- Low Gate Charge for Fast Switching
- Small 1.6 X 1.6 mm Footprint
- ESD Protected Gate
- We declare that the material of product is ROHS compliant and halogen free.

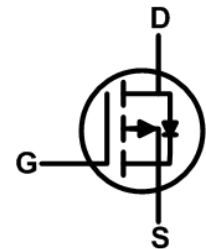
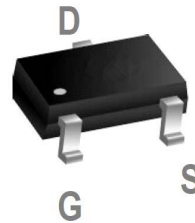
### Product Summary

BVDSS	RDSON	ID
30V	140mΩ	154mA

### Applications

- Power Management Load Switch
- Level Shift
- Portable Applications such as Cell Phones, Media Players, Digital Cameras, PDA's, Video Games, Hand Held Computers, etc.

### SOT-523 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	154	mA
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	120	mA
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	618	mA
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	300	mW
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---416		$^\circ C/W$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=100\mu A$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1mA$	---	0.05	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=4.5V, I_D=154mA$	---	1.4	7.0	$\Omega$
		$V_{GS}=2.5V, I_D=154mA$	---	2.3	7.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=100\mu A$	0.5	1.0	1.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	0.9	---	$mV/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1.0	$\mu A$
		$V_{DS}=20V, V_{GS}=0V, T_J=85^\circ\text{C}$	---	---	1.0	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 5V, V_{DS}=0V$	---	---	$\pm 1.0$	$\mu A$
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=0.1A$	---	80	---	mS
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=5V, V_{GS}=4.5V,$ $R_G=10\Omega, I_D=75mA$	---	13	---	ns
$T_r$	Rise Time		---	15	---	
$T_{d(off)}$	Turn-Off Delay Time		---	98	---	
$T_f$	Fall Time		---	60	---	
$C_{iss}$	Input Capacitance	$V_{DS}=5V, V_{GS}=0V, f=1MHz$	---	11.5	---	$\mu F$
$C_{oss}$	Output Capacitance		---	10	---	
$C_{rss}$	Reverse Transfer Capacitance		---	3.5	---	

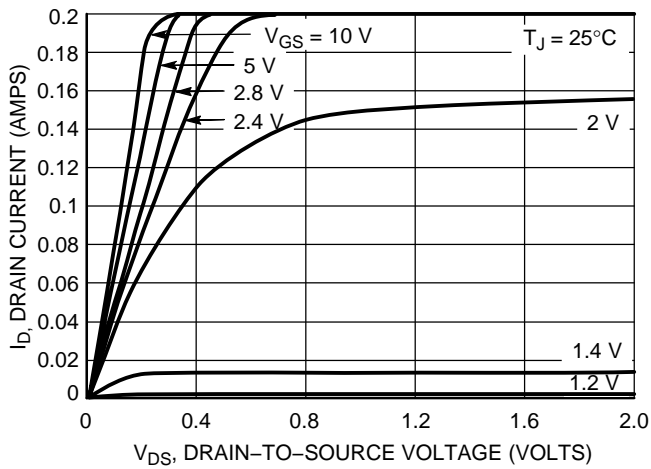
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	100	mA
$I_{SM}$	Pulsed Source Current <sup>2,4</sup>		---	---	0.4	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=0.154mA, T_J=25^\circ\text{C}$	---	0.77	0.9	V

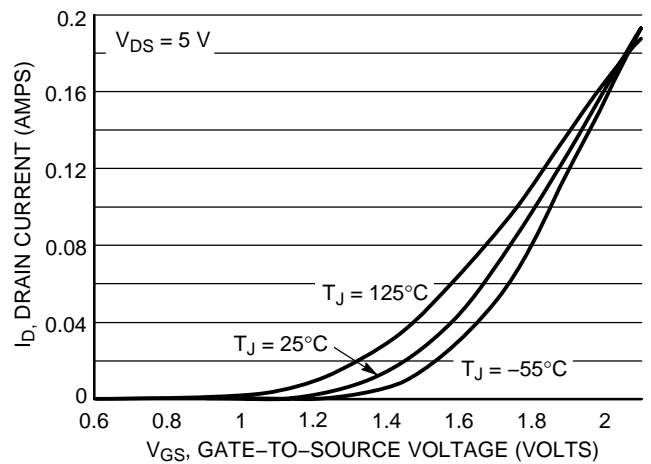
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

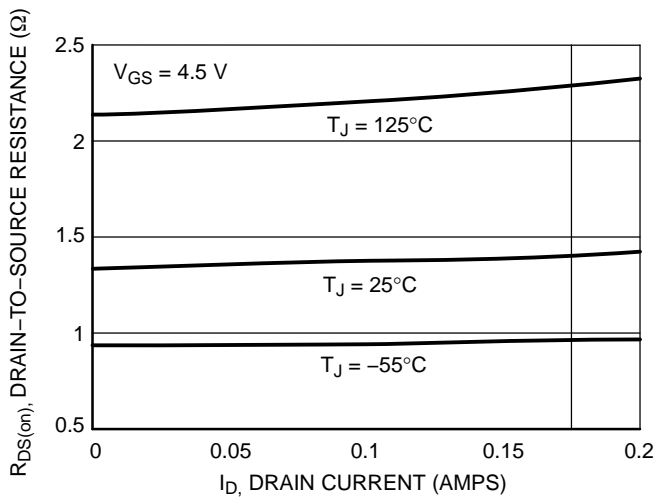
**Typical Performance Characteristics**



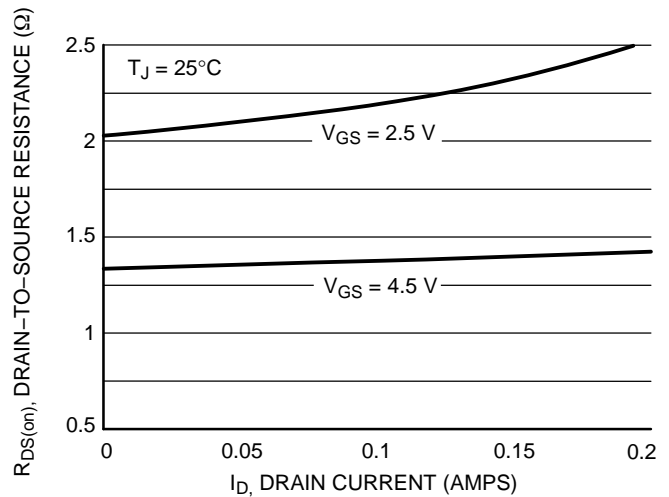
**On-Region Characteristics**



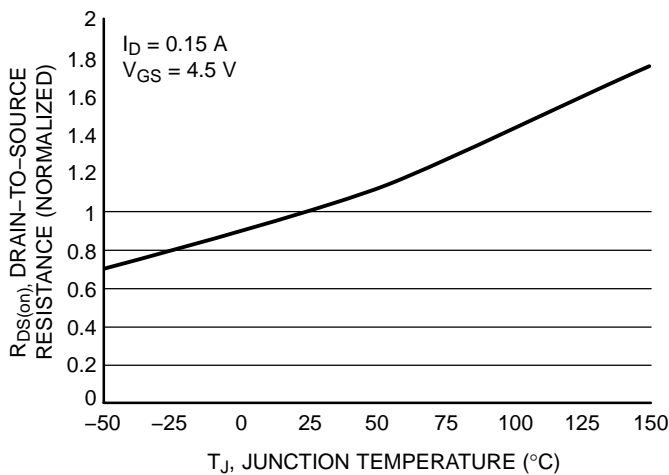
**Transfer Characteristics**



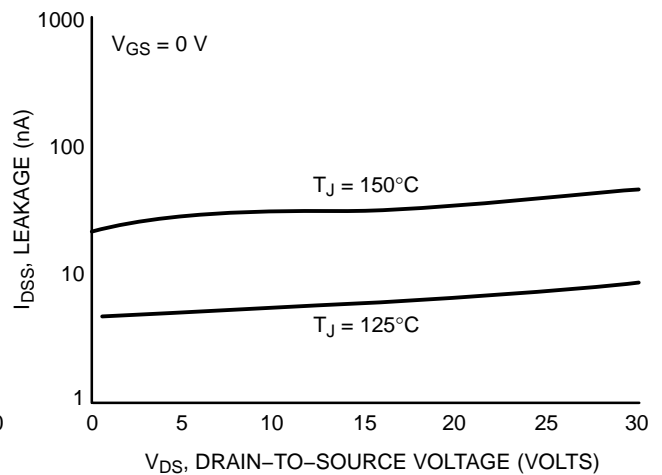
**On-Resistance vs. Drain Current and Temperature**



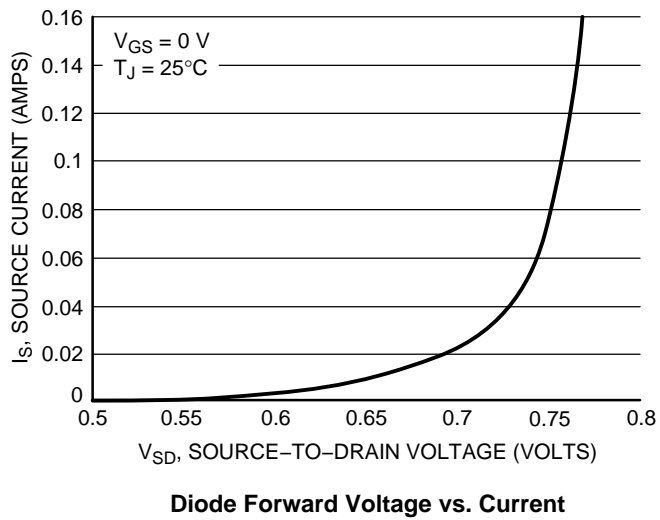
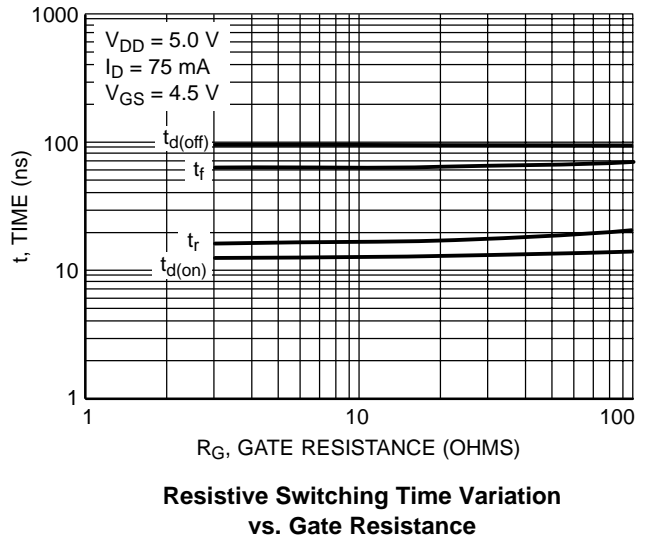
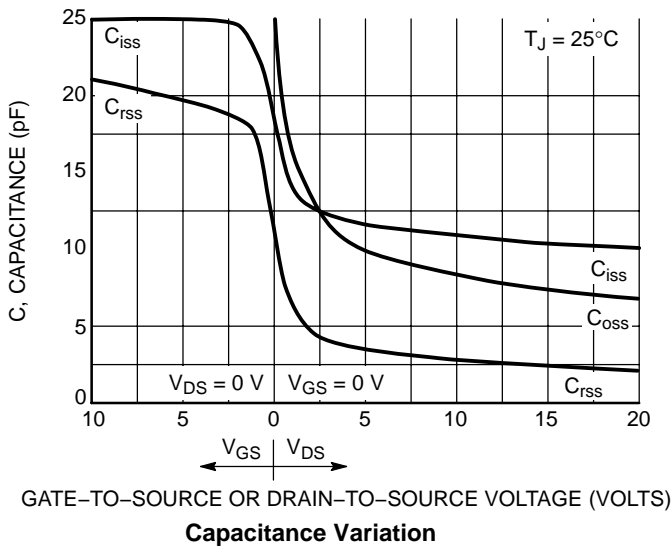
**On-Resistance vs. Drain Current and Gate Voltage**



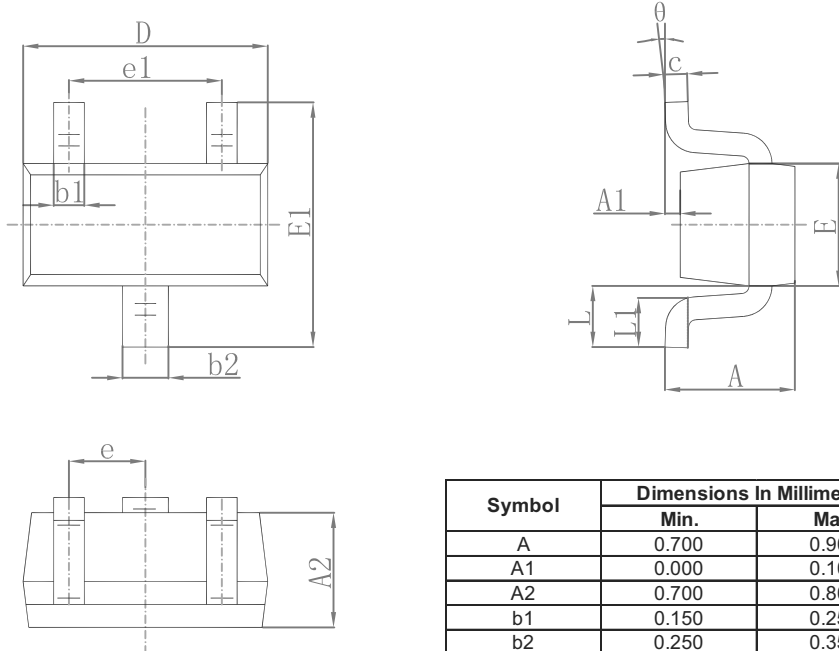
**On-Resistance Variation with Temperature**



**Drain-to-Source Leakage Current vs. Voltage**

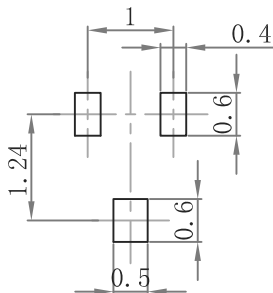


**SOT-523 Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
c	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
e	0.500 TYP.		0.020 TYP.	
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016 REF.	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°

**SOT-523 Suggested Pad Layout**





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